

Title (en)
MICROSTRUCTURE COMPRISING A SURFACE WHICH IS FUNCTIONALISED THROUGH THE LOCALISED DEPOSIT OF A THIN LAYER AND PRODUCTION METHOD THEREOF

Title (de)
MIKROSTRUKTUR MIT EINER FLÄCHE, DIE DURCH DIE LOKALISIERTE ABSCHIEDUNG EINER DÜNNEN SCHICHT FUNKTIONALISIERT IST, UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
MICROSTRUCTURE A SURFACE FONCTIONNALISEE PAR DEPOT LOCALISE D'UNE COUCHE MINCE ET PROCEDE DE FABRICATION ASSOCIE

Publication
EP 1551754 A2 20050713 (FR)

Application
EP 03792450 A 20030825

Priority
• FR 0350036 W 20030825
• FR 0210571 A 20020826

Abstract (en)
[origin: FR2843742A1] An electromechanical structure (1) incorporating a first mechanical part (102) made of a first conductive material and which includes an elastically deformable area (104) having a given thickness with an exposed surface (2) and a first organic film (4) with a given thickness, which is deposited over the entire exposed surface of the deformable area. The thickness of this first film is such that the elastic response of the deformable area including the first film does not change by more than 5% in relation to the response of the bare deformable area or the first film is ten times smaller than the thickness of the deformable area. Independent claims are also included for: (a) a pressure sensor incorporating an electromechanical microstructure; (b) a platelet incorporating an assembly of microstructures; (c) a microsystem incorporating an electromechanical microstructure.

IPC 1-7
B81B 3/00; **A61B 5/00**; **G01L 9/00**

IPC 8 full level
A61B 5/00 (2006.01); **B81B 3/00** (2006.01); **G01L 9/00** (2006.01)

CPC (source: EP US)
A61B 5/00 (2013.01 - EP US); **B81B 3/0094** (2013.01 - EP US); **G01L 9/0042** (2013.01 - EP US); **B29C 2043/5825** (2013.01 - EP US); **B81B 2201/0214** (2013.01 - EP US); **B81B 2201/0235** (2013.01 - EP US); **B81B 2201/0264** (2013.01 - EP US); **B81B 2201/06** (2013.01 - EP US); **B81B 2203/0127** (2013.01 - EP US); **H01L 2224/45144** (2013.01 - EP US); **H01L 2224/48091** (2013.01 - EP US); **H01L 2924/181** (2013.01 - EP US); **Y10S 977/733** (2013.01 - EP US)

C-Set (source: EP US)
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See references of WO 2004018349A2

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DOCDB simple family (application)
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